



Technical Data Sheet

INDUFLOOR®-IB2115

Conductive aqueous lacquer

Art.-No. 5 55014

Properties:

INDUFLOOR-IB2115 is a solvent free, pigmented, water emulsified two component epoxy resin with the following properties:

- high electrostatic charge dissipation
- good bond between coats.

Areas of application:

INDUFLOOR-IB2115 is used in combination with the copper strip INDU-ConductiveStrip as a conductive layer beneath conductive floor coverings and as a component within the INDUFLOOR-GWS 3 WHG system.

Technical Data:

Basis:	two component epoxy resin
Colour:	black
Mixing ratio:	1:5 parts by weight
Density:	approx. 1.10 g/cm ³ at +23° C
Viscosity:	approx. 6500 ± 500 mPa·s at +23° C
Pot life:	approx. 120 mins at +12° C approx. 60 mins at +20° C approx. 45 mins at +30° C
Substrate and application temperature:	min. approx. +12° C, max. approx. +30° C
Foot traffic after:	min. approx. 12 hrs at +23° C
Overcoat after:	approx. 12 hrs up to a max. 24 hrs at +23° C
Fully cured:	after approx. 7 days at +23° C
Electrical resistance:	< 10 ⁴ k Ω (DIN IEC 61340-4-1)

Substrate preparation:

The area to be treated must be:

- dry, firm, sound and have a good key

- free from separating and adhesion inhibiting substances such as dust, laitance, grease, oil, rubber marks, paint residues and similar
 - protected against moisture penetration from the rear.
- Use suitable means to prepare the substrate dependent on its condition such as e.g. shot blasting, planing, brushing, sweeping and vacuuming.

Product preparation:

Components A (resin) and B (hardener) are delivered in separate containers at a predetermined mixing ratio. Tip component A into component B. Ensure that the hardener drains completely from its container. Blend both components together with a suitable mixer at approx. 300 rpm (e.g. drill with paddle). It is important to also stir from the sides and the bottom to ensure that the hardener is evenly dispersed. Stir until the mix is homogenous (free from streaks); mixing time 5 minutes. The minimum temperature during the mixing process should be +15° C. **Do not use mixed material directly from the packaging.** Decant the material into a clean container and mix through thoroughly once again.

Method of application / consumption:

Roller apply INDUFLOOR-IB2115 in one coat. Pour the mixed material in sections on the surface and spread over the area using a double bladed rubber squeegee. Subsequently roll with a short nap fur roller to an even finish.

Consumption: approx. 150 – 200 g/m² dependent on the surface roughness.

Cleaning:

Thoroughly clean tools immediately after use with water.

Packaging:

12 kg containers. Components A and B (in separate containers) are delivered at a predetermined mixing ratio.

INDUFLOOR®-IB21 15

Storage & Shelf Life:

18 months when stored dry and cool above +10° C in the original unopened packaging.

Health & Safety:

Once cured INDUFLOOR-IB21 15 is considered harmless. Note: code of practice for handling epoxies distributed by the building industry professional association www.bgbau.de or www.gisbau.de.

Important advice:

- As a rule SCHOMBURG ICS GmbH products are supplied in working packs i.e. at a predetermined mixing ratio. With deliveries in large containers, part quantities will need to be weighed using scales. Always thoroughly stir the filled components and only then blend with the second component. This is to be carried out with a suitable rotary mixer e.g. Polyplan/Ronden mixing paddle or similar. In order to exclude mixing errors, decant into a clean container and remix. The mixing speed should be 300 – 400 rpm. Ensure that no air is entrained. Higher speeds drag unnecessary air quantities into the product whilst lower speeds do not result in a good blend or require too long a mix time (pot life). The temperature of the components should be at a minimum of +15° C. This is also applicable to any fillers, e.g. sand, to be mixed in. The addition of any fillers is carried out after both liquids have been blended. Afterwards tip the completely mixed material immediately onto the prepared substrate and promptly thoroughly spread in accordance with the instructions in the technical data sheet. Always stir one component products before using.
- The application temperature may not fall below +10° C nor exceed +40° C.
- Higher temperatures shorten the pot life. Lower temperatures increase the pot life and curing time. Material consumption is also increased at lower temperatures.
- To increase pot life/working time at higher temperatures, store material in a cool environment above

+10° C until ready for use. Only expose to warm temperatures just before mixing.

- Waiting time between successive coats – min. 12 hours up to a max. 24 hours. At higher relative humidity > 75% the waiting time should be lengthened accordingly.
- Ensure there is adequate ventilation and extraction during the drying and curing phases.
- The bond between the individual coats can be heavily impeded through the influence of moisture or contamination between successive applications. The substrate temperature must be a minimum of < 3° C above the dew point temperature.
- Applications that are too thick (greater material consumption) lead to higher electrical resistance, to crack formation and debonding.
- Protect surface protective systems from moisture (e.g. rain) for approx. 4 – 6 hours after application. Dampness produces a white discolouration and/or stickiness on the surface and can impede the cure. Discoloured and/or sticky surfaces should be taken off e.g. by abrading and renewed.
- Applications that are not clearly explained in this technical data sheet may only be carried out after consultation with and written confirmation from the Technical Services Department of SCHOMBURG ICS GmbH.
- Cured product residues are to be disposed of under waste disposal classification 57123 "Epoxy resin".

Please observe a valid EU safety data sheet.

Paint products directive (2004/42/EC)

Group Wb: j

Level 1 (2007): max. 140 g/l

Level 2 (2010): max. 140 g/l

INDUFLOOR-IB21 15 contains: < 140 g/l

GISCODE: RE 2 (component A)